

## REMARKS

Prior to establishing a *prima facie* rejection, the applicant is under no duty to respond. Here, two references are discussed, but no theory or rationale to combine them is ever provided. Thus a *prima facie* rejection is not made out. Therefore, there is no duty or obligation on the applicant to further respond.

Nonetheless, it is noted that neither reference teaches applying row and column electrodes to such sheet while such sheet is held in the flattened configuration. In fact, this would be impossible because of the imposition of the cover 131 over the OLED 11. That is, until the apparatus 30 is removed, it would not be possible to apply row and column electrodes. Applying electrodes after the alleged flattening force is removed would not meet the claim limitation.

And even after the apparatus is removed, it is not clear whether the row and column electrodes could still be applied. That is because the reference is completely silent about whether row and column electrodes exist. For example, within the OLED 11, normally row and column electrodes would be applied between different cells within the OLED 11. That would mean that the row and column electrodes were already existent before the apparatus 30 shown in the cited reference was applied. Therefore, the reference could not possibly meet the claim limitations.

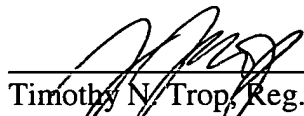
Alternatively, once the face plate 131 and flattening force are applied, it would be impossible to apply row and column electrodes to the OLED under the face plate.

The additionally cited reference has no pertinency in this regard. Thus, it can be seen that not only is no *prima facie* rejection made out, but it would be impossible to make out a *prima facie* rejection with the two cited references.

Therefore, reconsideration would be appropriate.

Respectfully submitted,

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